



SOD68

hermetically sealed glass package; axial leaded; 2 leads

8 February 2016

Package information

1. Package summary

Terminal position code	A (axial)
Package type descriptive code	DO-34
Package type industry code	DO-34
Package style descriptive code	LALF (glass axial (leaded) long form)
Package style suffix code	NA (not applicable)
Package body material type	L (glass)
JEDEC package outline code	DO-34
Mounting method type	T (through-hole mount)
Issue date	9-6-1997

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	[tbd]	-	3.04	3.04	mm
Φ D	package diameter	[tbd]	-	1.6	1.6	mm
n ₂	actual quantity of termination	-	-	2	-	



2. Package outline

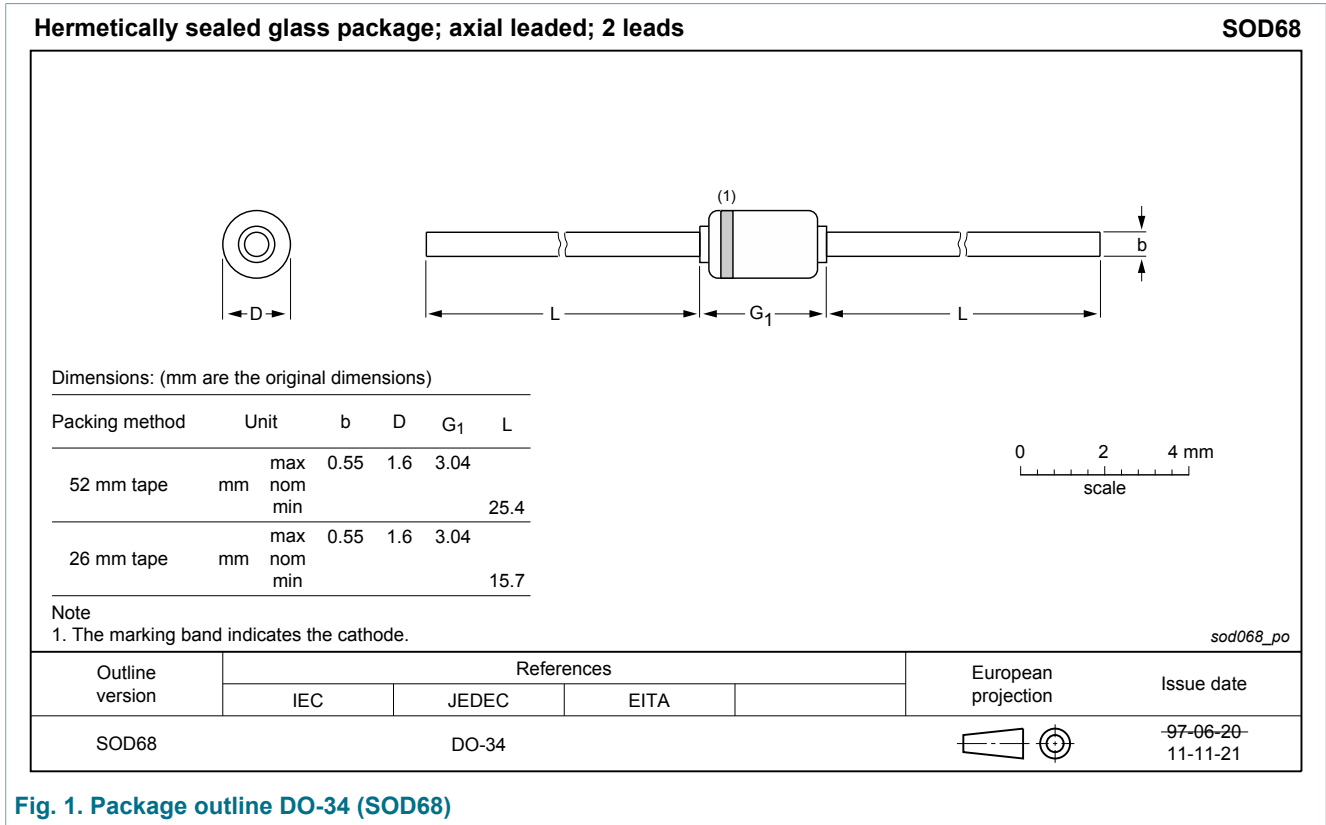


Fig. 1. Package outline DO-34 (SOD68)

3. Legal information

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